

(1,00 mm) .0394" **SAL1 SERIES** 



# **HIGH SPEED MICRO PLANE SOCKET**

### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material: Black LCP
Contact Material: BeCu

BeCu
Plating:
Au or Sn over
50μ" (1,27 μm) Ni
Operating Temp:
-55°C to +125°C
Current Rating:
2.3 A per contact @ 80°C
BOHS Compliant:

RoHS Compliant: **Processing:** 

Lead-Free Solderable: SMT Lead Coplanarity: (0,10 mm) .004" max

#### Mates with:

(1,60 mm) .062" or (2,40 mm) .093" card

#### **APPLICATION SPECIFIC OPTION**

Heavy Gold plating available. Call Samtec.

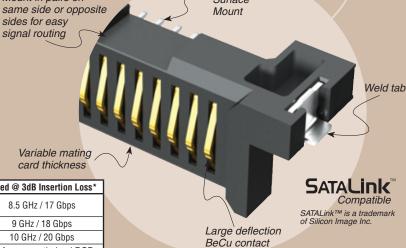
or contact sig@samtec.com

Variable mating

Mount in pairs on

sides for easy

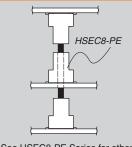
signal routing



Surface

SALT		Rated @ 30B Insertion Loss^
Single-Ended Signaling	Top or Bottom	8.5 GHz / 17 Gbps
Differential Pair Signaling	Тор	9 GHz / 18 Gbps
Differential Pair Signaling	Bottom	10 GHz / 20 Gbps
*Performance data includes effects of a non-optimized PCB.		
Complete test data available at www.samtec.com?SAL1		

#### ALSO AVAILABLE



See HSEC8-PE Series for other

card pass-through options.

## **APPLICATIONS**



Same side mount

Note: While optimized for  $50\Omega$  applications, this connector with alternative signal/ground patterns may also perform well in certain 75 $\Omega$  applications. Contact

Samtec for further information. Note: Some lengths, styles and options are non-standard, non-returnable.



NO. OF 01 **POSITIONS** 

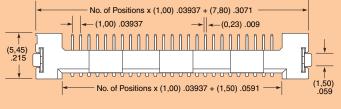
**PLATING OPTION** 

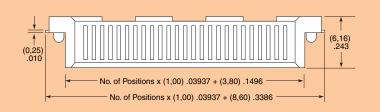
=Tape &

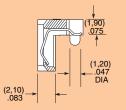
20, 27, 30, 40

= 30μ" (0,76 μm) Gold on contact,

Note: Other Gold plating options available. Contact Samtec.







Due to technical progress, all designs, specifications and components are subject to change without notice.

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